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N-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(m\Omega)(Typ.)$	I _D (A) ^a	Q _g (Typ.)			
30	3.6 at V _{GS} = 10 V	85	34.5 nC			
30	5.5 at V _{GS} = 4.5 V	05				

FEATURES

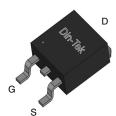
- DT-Trench Power MOSFET
- 100 % R_g and UIS Tested
- High Current Capability
- RoHS and Halogen-Free Compliant

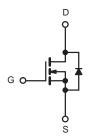
Pb RoHS

APPLICATIONS

- DC/DC Converters in Computing
- Isolated DC/DC Converters in Telecom and Industrial







N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	V _{DS}	30	V		
Gate-Source Voltage	V _{GS}	± 20	¬		
Continuous Drain Current (T _{.I} = 150 °C) ^a	T _C = 25 °C		85		
Continuous Drain Current (T) = 150 °C)	T _C = 100 °C	l _D	63	А	
Pulsed Drain Current ^b	I _{DM}	340			
Single Avalanche Energy	E _{AS}	160	mJ		
Maximum Power Dissipation ^c	T _C = 25 °C	P _D	68	W	
Maximum Fower Dissipation	T _C = 100 °C	PD PD	21.2		
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to + 150	°C		

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	LIMIT	UNIT		
Junction-to-Ambient (PCB Mount) ^d	R_{thJA}	50	°C/W		
Junction-to-Case (Drain)	R _{thJC}	1.84	- 10/00		

Notes

- a. Calculated continuous current based on maximum allowablejunction temperature.
- b. Repetitive rating; pulse width limited by max. junction temperature.
- c. $\,$ Pd is based on max. junction temperature, using junction-case thermal resistance.
- d. The value of R_{8JA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper,in a still air environment with Ta=25 °C.



PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	30	-	-	V	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1	-	3		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA	
7 0 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	I _{DSS}	$V_{DS} = 30 V, V_{GS} = 0 V$	-	-	1	μА	
Zero Gate Voltage Drain Current		V _{DS} = 24 V, V _{GS} = 0 V, T _J = 55 °C	-	-	10		
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 10 V	85	-	-	Α	
Drain Course On State Registered 3	В	V _{GS} = 10 V, I _D = 20 A	-	3.6	4.5	mΩ	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 15 A	-	5.5	7.2		
Forward Transconductance ^a	9fs	$V_{DS} = 5 \text{ V}, I_{D} = 20 \text{ A}$	-	45	-	S	
Dynamic ^b							
Input Capacitance	C _{iss}		-	1750	-	pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 15 \text{ V}, f = 1 \text{ MHz}$	-	188	-		
Reverse Transfer Capacitance	C _{rss}		-	173	-		
Total Gate Charge ^c	Q_g		-	34.5	-	nC	
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	-	2.8	-		
Gate-Drain Charge ^c	Q_{gd}		-	5.6	-		
Gate Resistance	R_g	f = 1 MHz	-	2.8	-	Ω	
Turn-On Delay Time ^c	t _{d(on)}		-	7.5	-		
Rise Time ^c	t _r	$V_{DD} = 15 \text{ V}, I_D = 20 \text{ A}, R_g = 3 \Omega$	-	12	-	ns	
Turn-Off Delay Time ^c	t _{d(off)}	$V_{GS} = 10 \text{ V}$, $R_L = 1 \Omega$	-	30	-		
Fall Time ^c	t _f		-	9.5	-		
Drain-Source Body Diode Ratings and Characteristics ^b (T _C = 25 °C)							
Continuous Source-Drain Diode Current	Is	T _C = 25 °C	-	-	85	Α	
Pulsed Current	I _{SM}		-	-	340	Α	
Forward Voltage ^a	V_{SD}	I _F = 1 A, V _{GS} = 0 V	-	-	1.2	V	
Reverse Recovery Time	t _{rr}	I _F = 20 A, di/dt = 100 A/μs	-	11	-	ns	
Reverse Recovery Charge	Q _{rr}	i _F = 20 A, αι/αι – 100 Α/μς	-	15	-	nC	

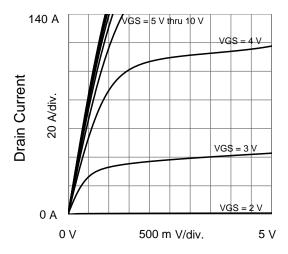
Notes

- a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

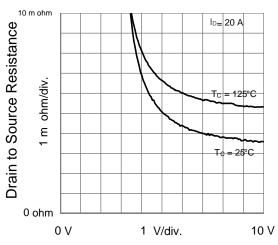
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those in dicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended pe riods may affect device reliability.



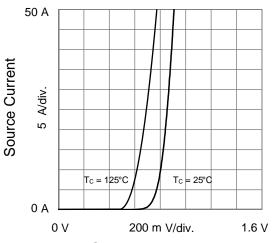
TYPICAL CHARAC TERISTICS (25 °C, unless otherwise noted)



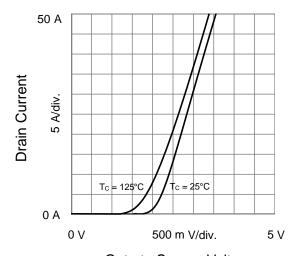
Drain to Source Voltage Output Characteristics



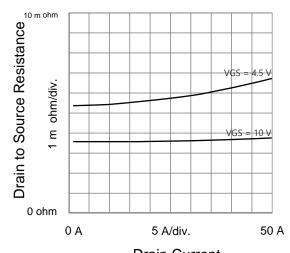
Gate to Source Voltage
Drain to Source Resistance vs. Gate to Source Voltag



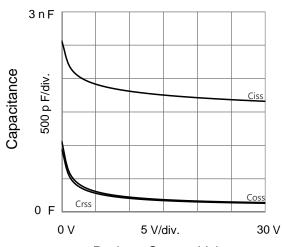
Source to Drain Voltage Body Diode Forward Characteristics



Gate to Source Voltage Transfer Characteristics



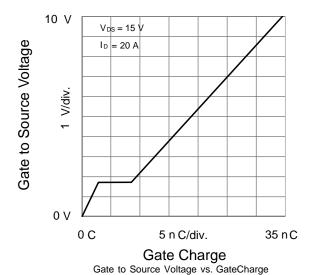
Drain Current

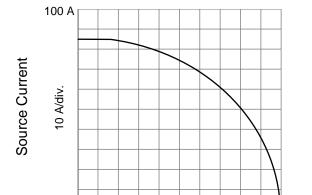


Drain to Source Voltage Capacitances



TYPICAL CHARAC TERISTICS (25 °C, unless otherwise noted)

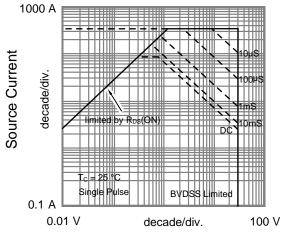




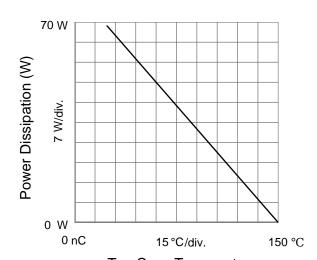
0 A

0 nC

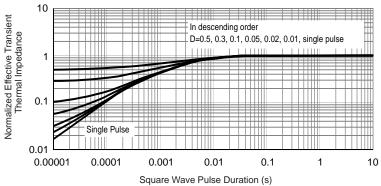
 $\label{eq:TC-div} \mbox{$^{\circ}$C/div.}$ $\mbox{$T_{C}$ - Case Temperature}$



Source to Drain Voltage Safe Operating Area, Junction-to-Case



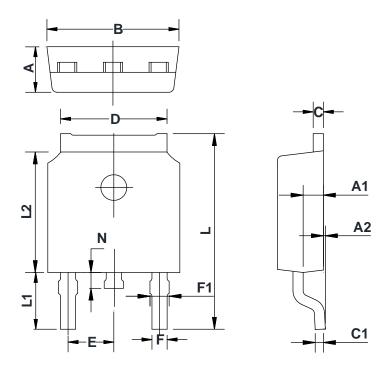
T_C - Case Temperature



150 °C

Normalized Thermal Transient Impedance, Junction-to-Case

TO-252-2L PACKAGE OUTLINE



COMMON DIMENSIONS (UNITS OF MEA SURE=MILLIMETER)

Symbol	Min	Тур	Max
А	2.10	2.30	2.50
A1	0.88	1.01	1.16
A2	0.00	0.15	0.28
В	6.40	6.60	6.80
С	0.42	0.50	0.63
C1	0.42	0.50	0.63
D	5.08	5.32	5.65
E	2.286 TYP		
F	0.63	0.76	0.89
F1	0.64	0.86	1.08
L	9.30	9.90	10.80
L1	2.40	2.80	3.60
L2	5.90	6.10	6.55
N	0.57	0.80	1.05





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